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SECTION 1. GENERAL

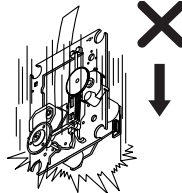
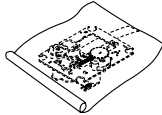
□ SERVICING PRECAUTIONS

NOTES REGARDING HANDLING OF THE PICK-UP

1. Notes for transport and storage

- 1) The pick-up should always be left in its conductive bag until immediately prior to use.
- 2) The pick-up should never be subjected to external pressure or impact.

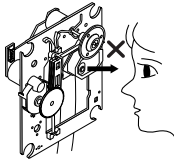
Storage in conductive bag



Drop impact

2. Repair notes

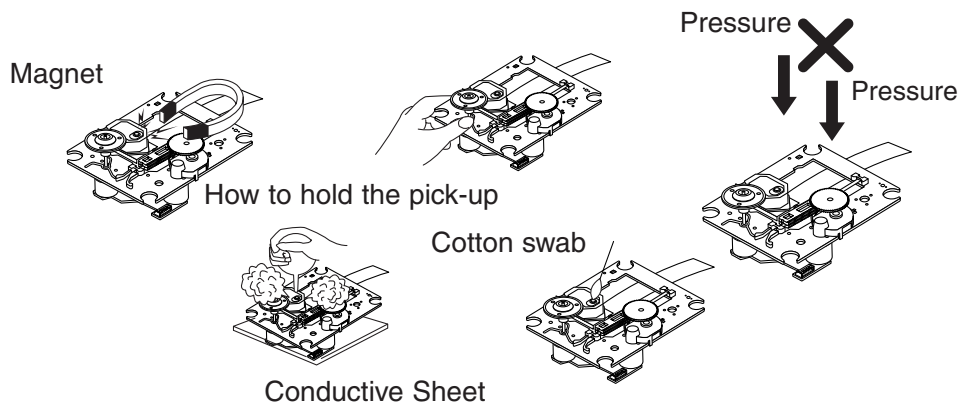
- 1) The pick-up incorporates a strong magnet, and so should never be brought close to magnetic materials.
- 2) The pick-up should always be handled correctly and carefully, taking care to avoid external pressure and impact. If it is subjected to strong pressure or impact, the result may be an operational malfunction and/or damage to the printed-circuit board.
- 3) Each and every pick-up is already individually adjusted to a high degree of precision, and for that reason the adjustment point and installation screws should absolutely never be touched.
- 4) Laser beams may damage the eyes!
Absolutely never permit laser beams to enter the eyes!
Also NEVER switch ON the power to the laser output part (lens, etc.) of the pick-up if it is damaged.



NEVER look directly at the laser beam, and don't let contact fingers or other exposed skin.

5) Cleaning the lens surface

If there is dust on the lens surface, the dust should be cleaned away by using an air bush (such as used for camera lens). The lens is held by a delicate spring. When cleaning the lens surface, therefore, a cotton swab should be used, taking care not to distort this.



6) Never attempt to disassemble the pick-up.

Spring by excess pressure. If the lens is extremely dirty, apply isopropyl alcohol to the cotton swab. (Do not use any other liquid cleaners, because they will damage the lens.) Take care not to use too much of this alcohol on the swab, and do not allow the alcohol to get inside the pick-up.

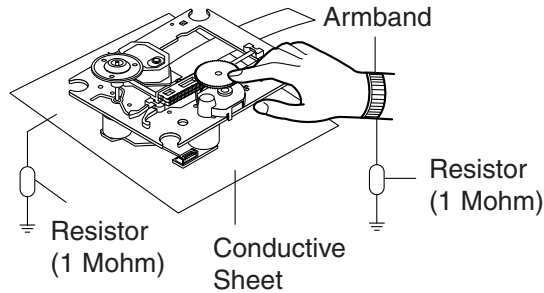
NOTES REGARDING COMPACT DISC PLAYER REPAIRS

1. Preparations

- 1) Compact disc players incorporate a great many ICs as well as the pick-up (laser diode). These components are sensitive to, and easily affected by, static electricity. If such static electricity is high voltage, components can be damaged, and for that reason components should be handled with care.
- 2) The pick-up is composed of many optical components and other high-precision components. Care must be taken, therefore, to avoid repair or storage where the temperature or humidity is high, where strong magnetism is present, or where there is excessive dust.

2. Notes for repair

- 1) Before replacing a component part, first disconnect the power supply lead wire from the unit
- 2) All equipment, measuring instruments and tools must be grounded.
- 3) The workbench should be covered with a conductive sheet and grounded.
When removing the laser pick-up from its conductive bag, do not place the pick-up on the bag. (This is because there is the possibility of damage by static electricity.)
- 4) To prevent AC leakage, the metal part of the soldering iron should be grounded.
- 5) Workers should be grounded by an armband (1M Ω)
- 6) Care should be taken not to permit the laser pick-up to come in contact with clothing, in order to prevent static electricity changes in the clothing to escape from the armband.
- 7) The laser beam from the pick-up should NEVER be directly facing the eyes or bare skin.



□ ESD PRECAUTIONS

Electrostatically Sensitive Devices (ESD)

Some semiconductor (solid state) devices can be damaged easily by static electricity. Such components commonly are called Electrostatically Sensitive Devices (ESD). Examples of typical ESD devices are integrated circuits and some field-effect transistors and semiconductor chip components. The following techniques should be used to help reduce the incidence of component damage caused by static electricity.

1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any electrostatic charge on your body by touching a known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device, which should be removed for potential shock reasons prior to applying power to the unit under test.
2. After removing an electrical assembly equipped with ESD devices, place the assembly on a conductive surface such as aluminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
3. Use only a grounded-tip soldering iron to solder or unsolder ESD devices.
4. Use only an anti-static solder removal device. Some solder removal devices not classified as "anti-static" can generate electrical charges sufficient to damage ESD devices.
5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ESD devices.
6. Do not remove a replacement ESD device from its protective package until immediately before you are ready to install it. (Most replacement ESD devices are packaged with leads electrically shorted together by conductive foam, aluminum foil or comparable conductive materials).
7. Immediately before removing the protective material from the leads of a replacement ESD device, touch the protective material to the chassis or circuit assembly into which the device will be installed.

CAUTION : BE SURE NO POWER IS APPLIED TO THE CHASSIS OR CIRCUIT, AND OBSERVE ALL OTHER SAFETY PRECAUTIONS.

8. Minimize bodily motions when handling unpackaged replacement ESD devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity sufficient to damage an ESD device).

CAUTION. GRAPHIC SYMBOLS



THE LIGHTNING FLASH WITH APROWHEAD SYMBOL. WITHIN AN EQUILATERAL TRIANGLE, IS INTENDED TO ALERT THE SERVICE PERSONNEL TO THE PRESENCE OF UNINSULATED "DANGEROUS VOLTAGE" THAT MAY BE OF SUFFICIENT MAGNITUDE TO CONSTITUTE A RISK OF ELECTRIC SHOCK.

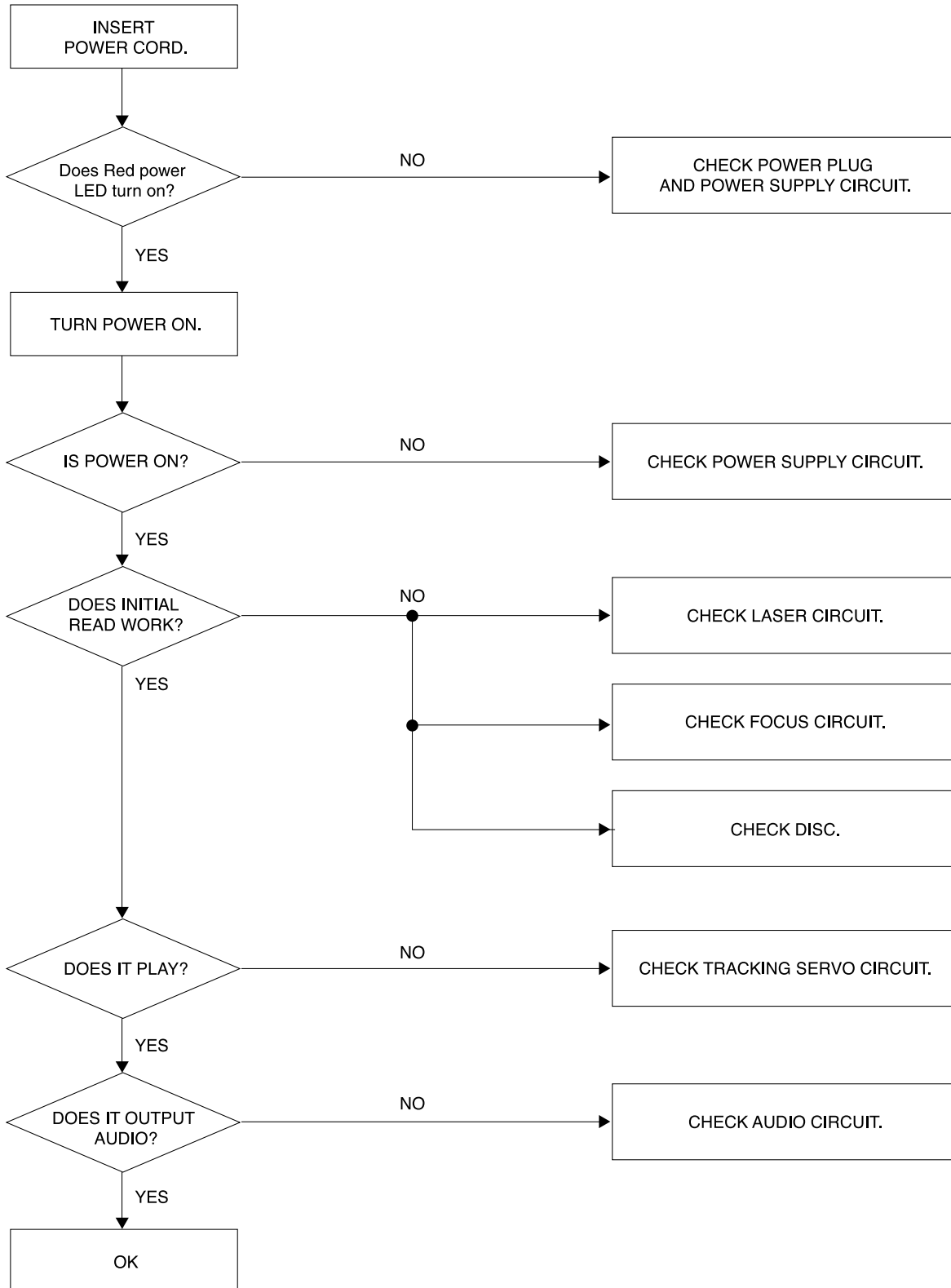


THE EXCLAMATION POINT WITHIN AN EQUILATERAL TRIANGLE IS INTENDED TO ALERT THE SERVICE PERSONNEL TO THE PRESENCE OF IMPORTANT SAFETY INFORMATION IN SERVICE LITERATURE.

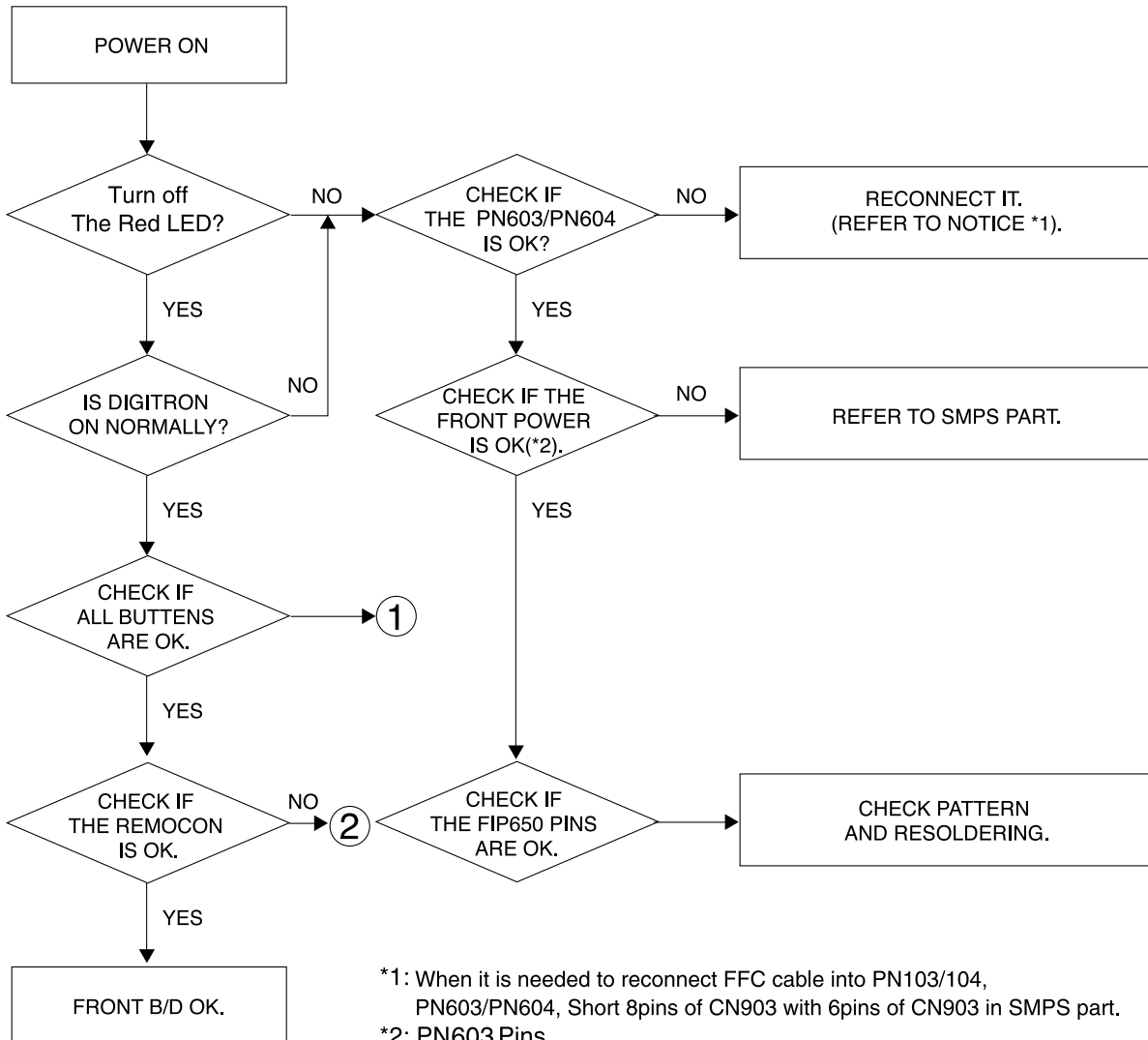
SECTION 2. AUDIO PART

□ AUDIO TROUBLESHOOTING GUIDE

1. POWER SUPPLY CIRCUIT



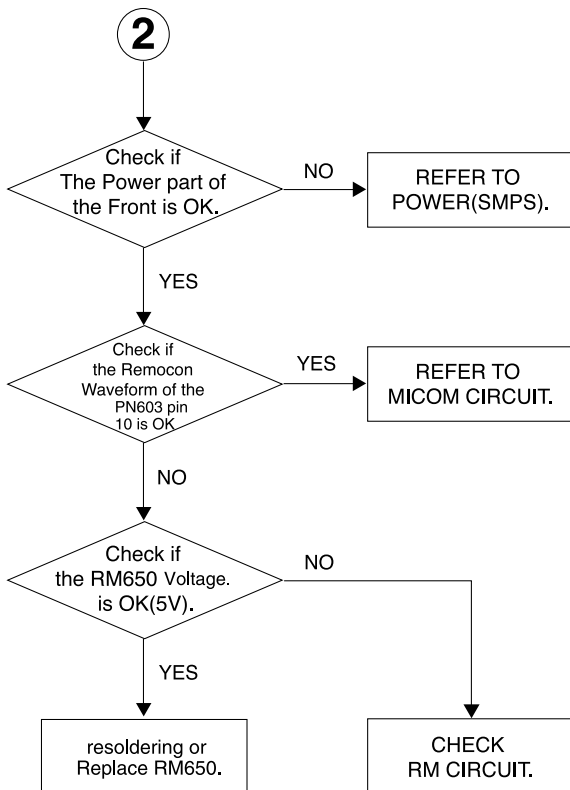
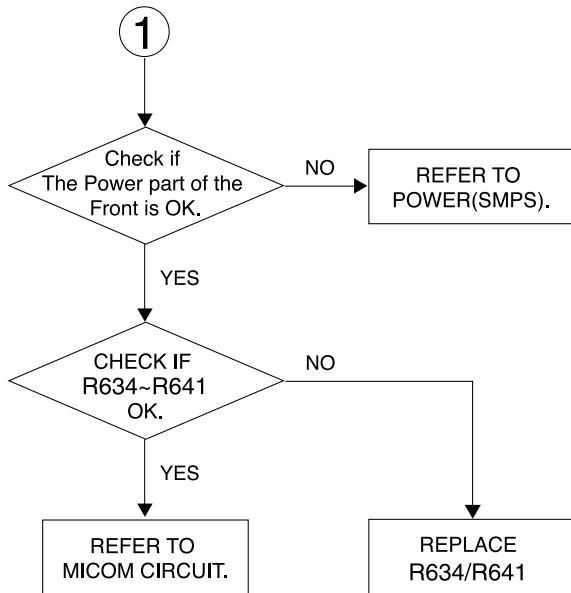
2. FRONT CIRCUIT (1/2)



*1: When it is needed to reconnect FFC cable into PN103/104,
PN603/PN604, Short 8pins of CN903 with 6pins of CN903 in SMPS part.

*2: PN603 Pins.
 PIN1 : -32.4
 PIN2 : -27.5
 PIN3 : -23.7
 PIN4 : -23.7
 PIN11 : -5.0

3. FRONT CIRCUIT (2/2)

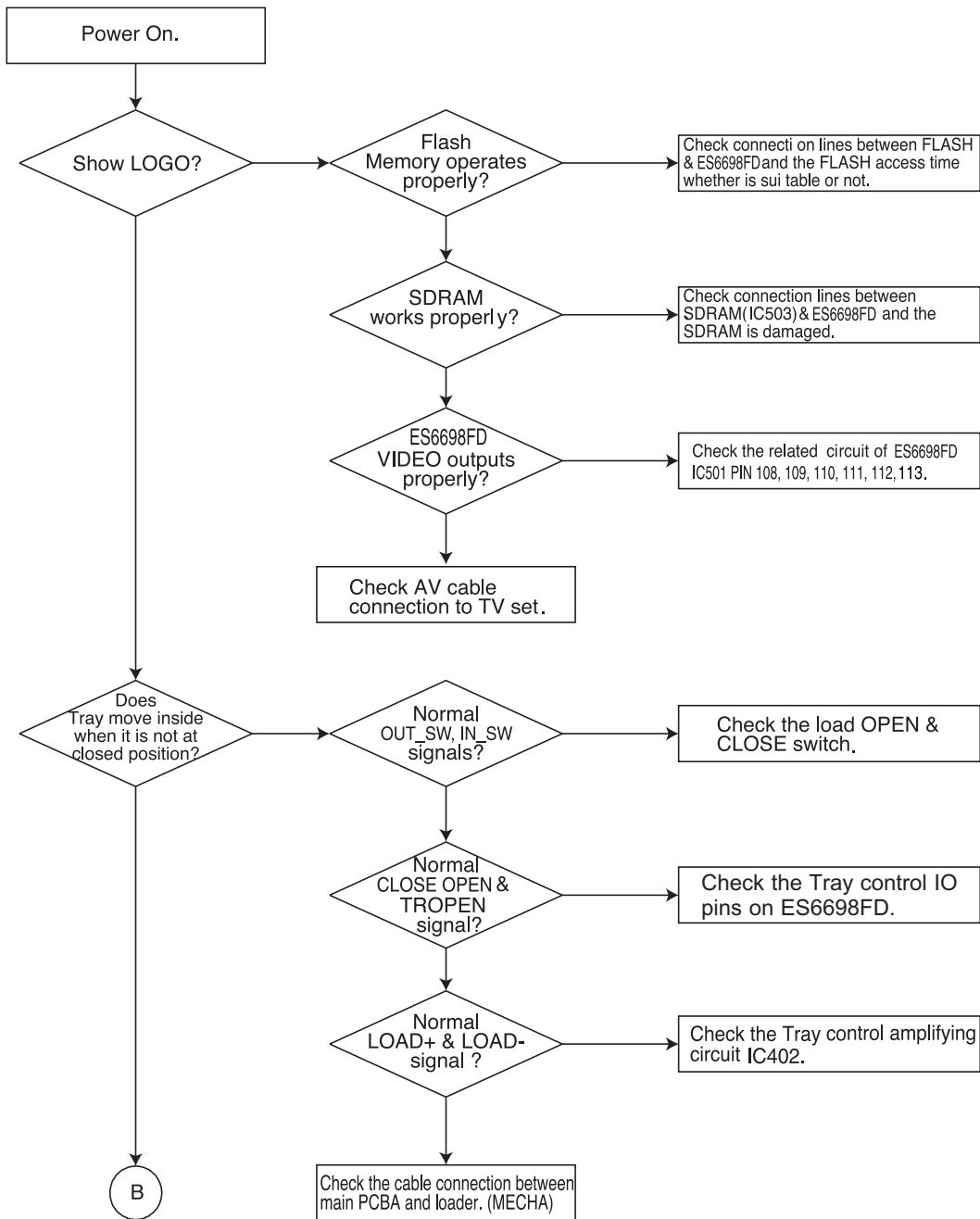


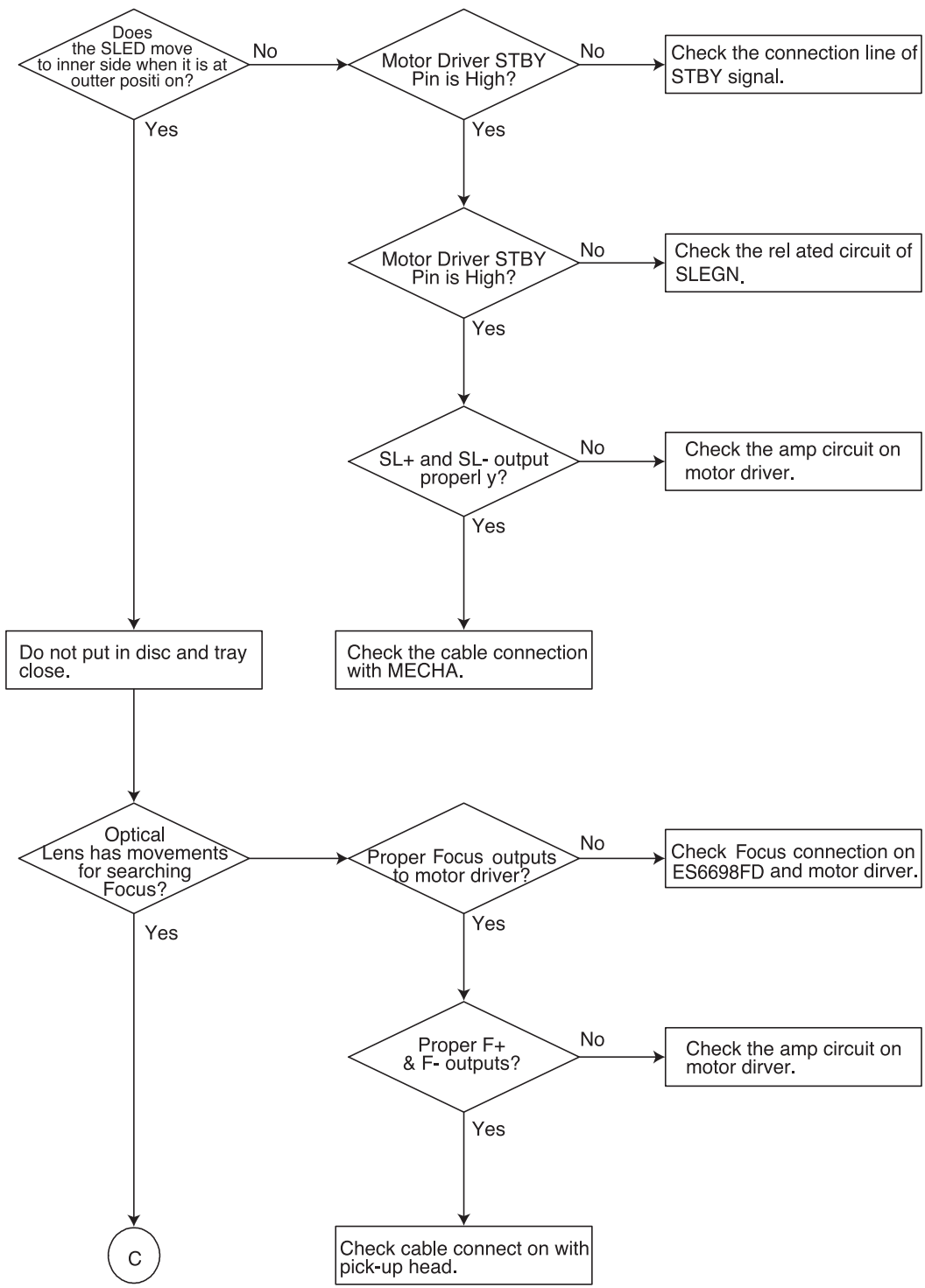
MEMO

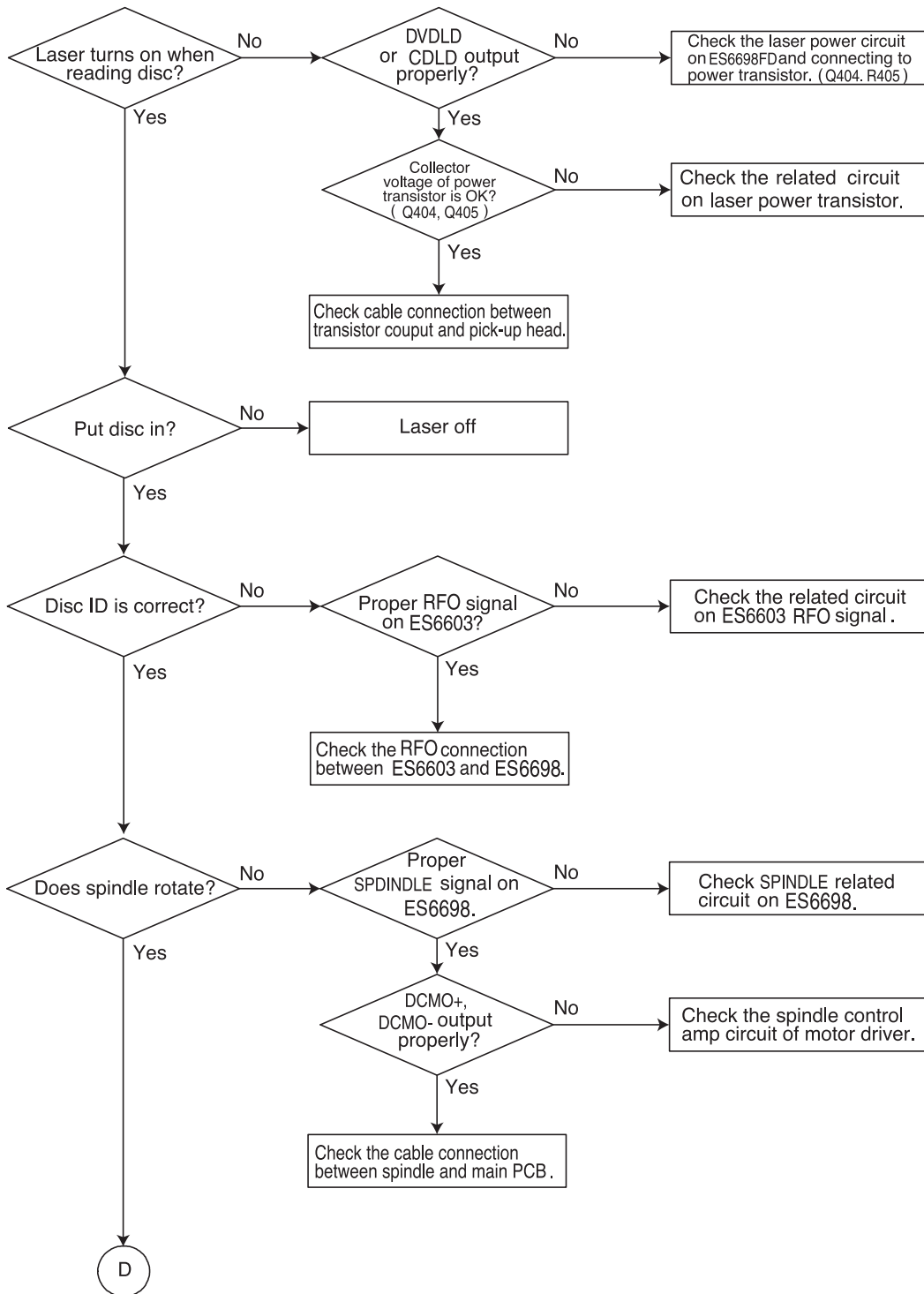
SECTION 3. DVD PART

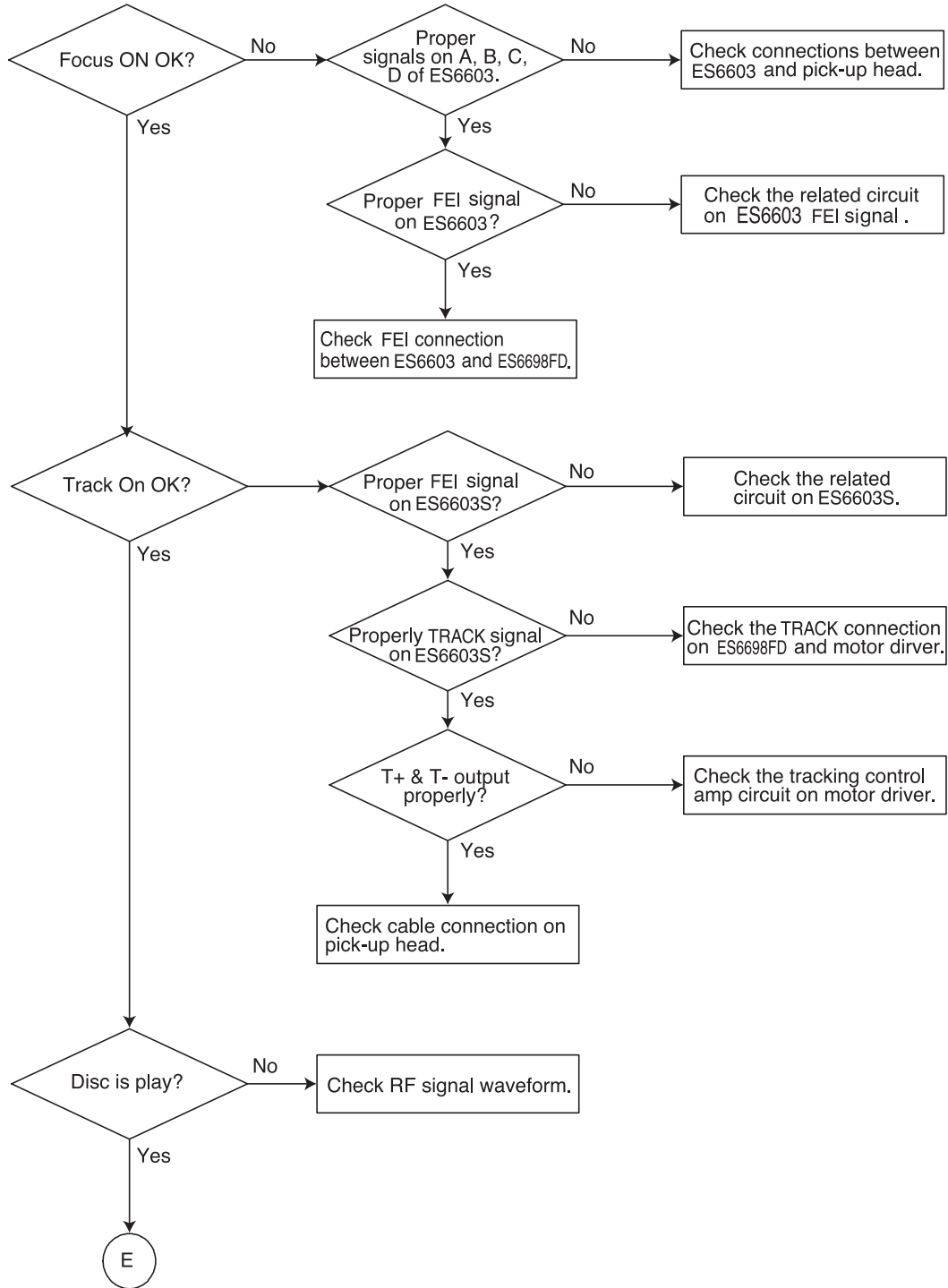
TROUBLESHOOTING GUIDE

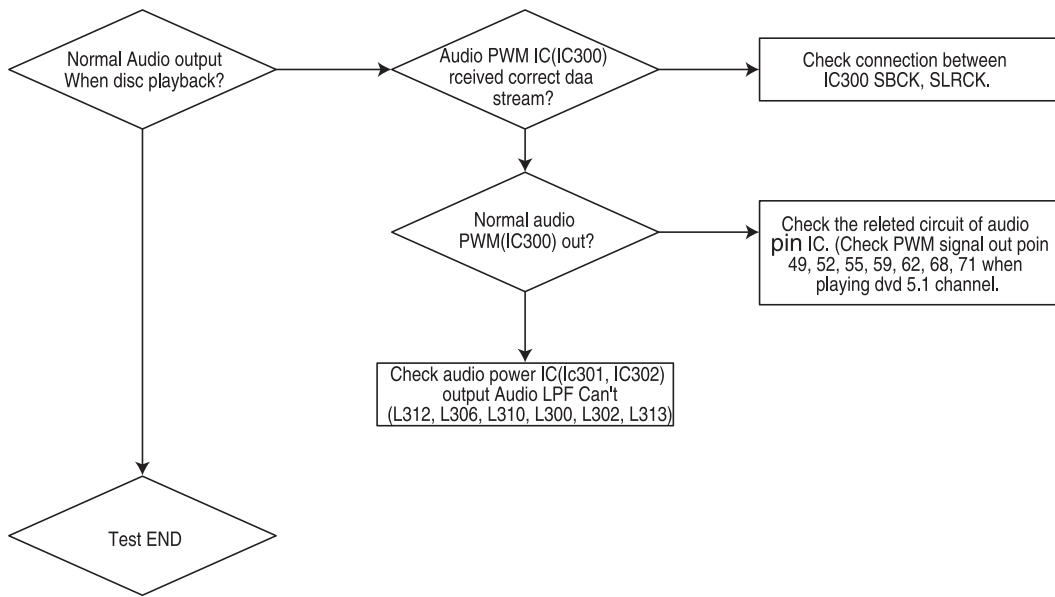
1. Test & debug flow





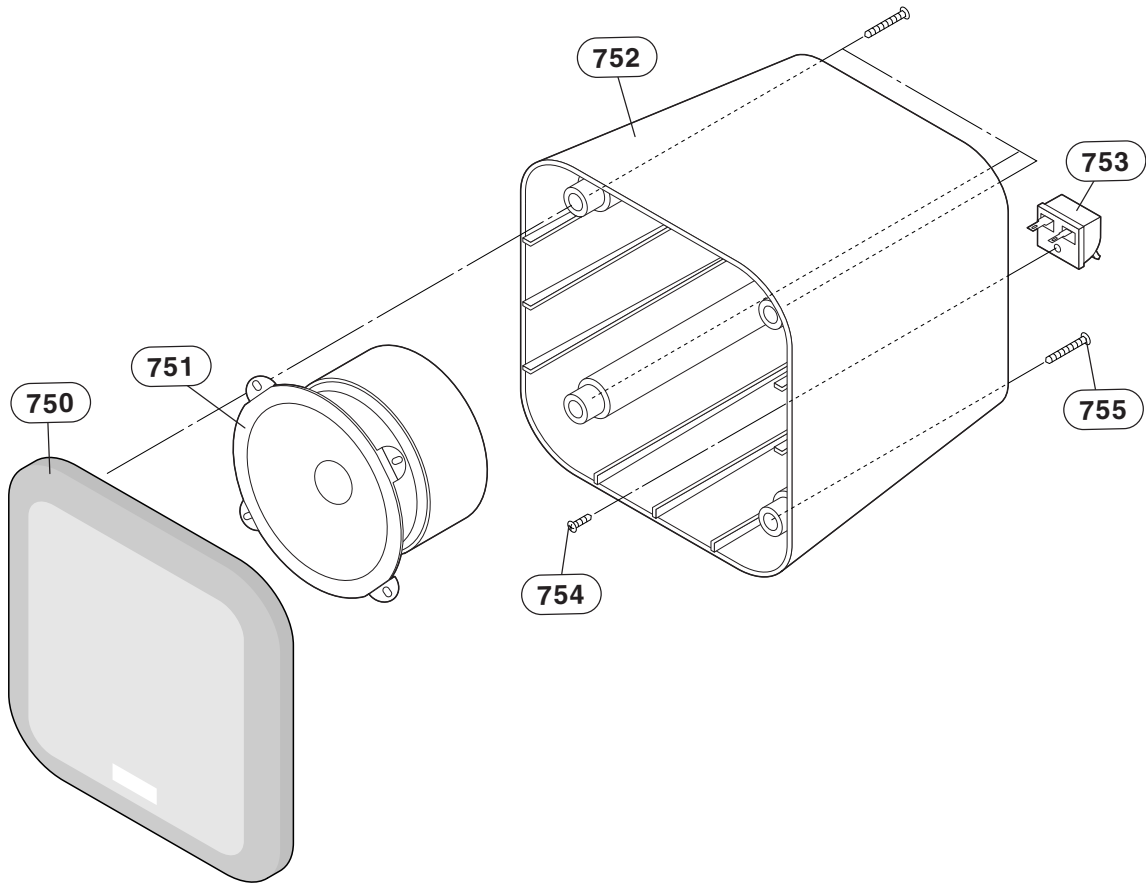




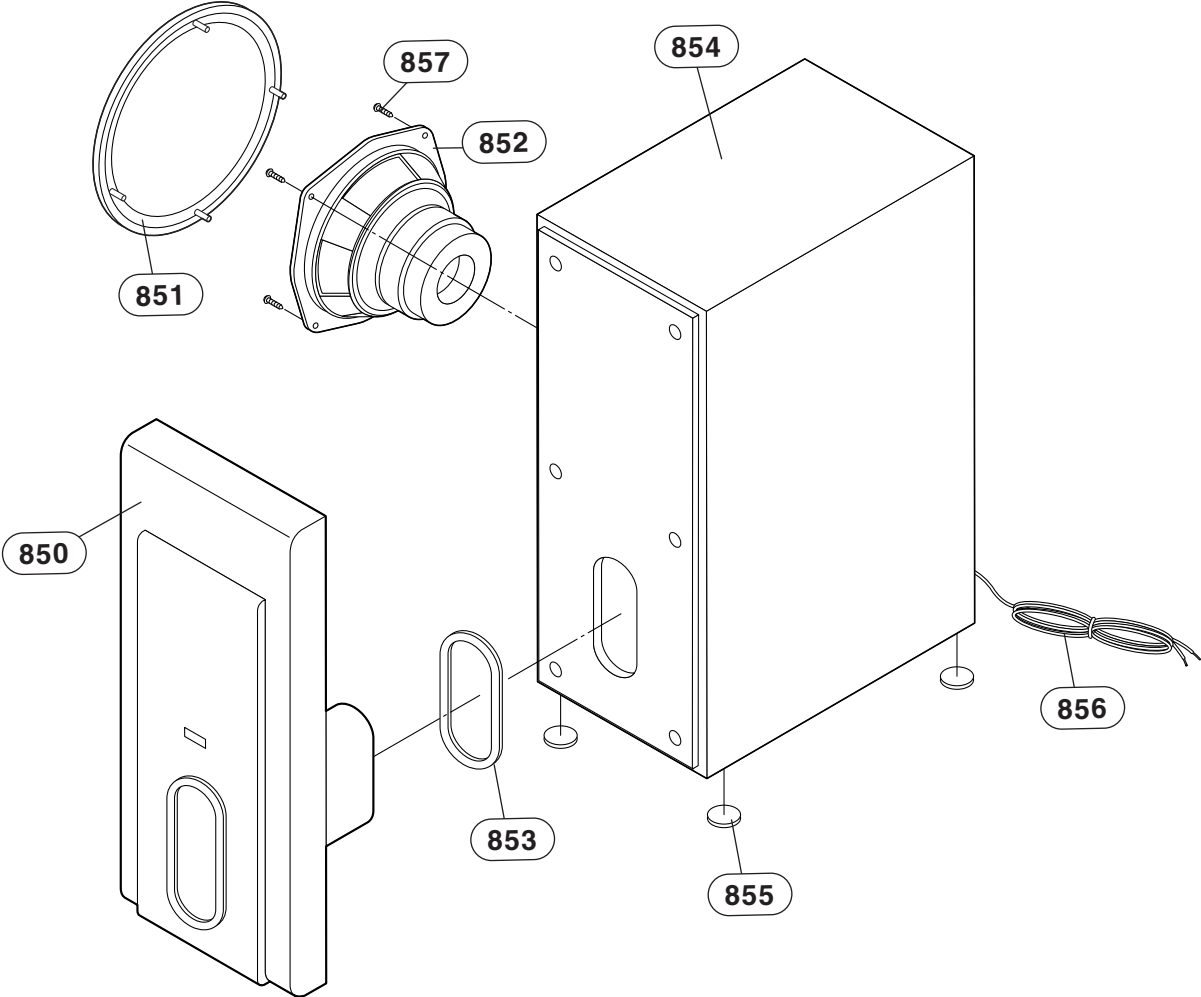


SECTION 5. SPEAKER SECTION

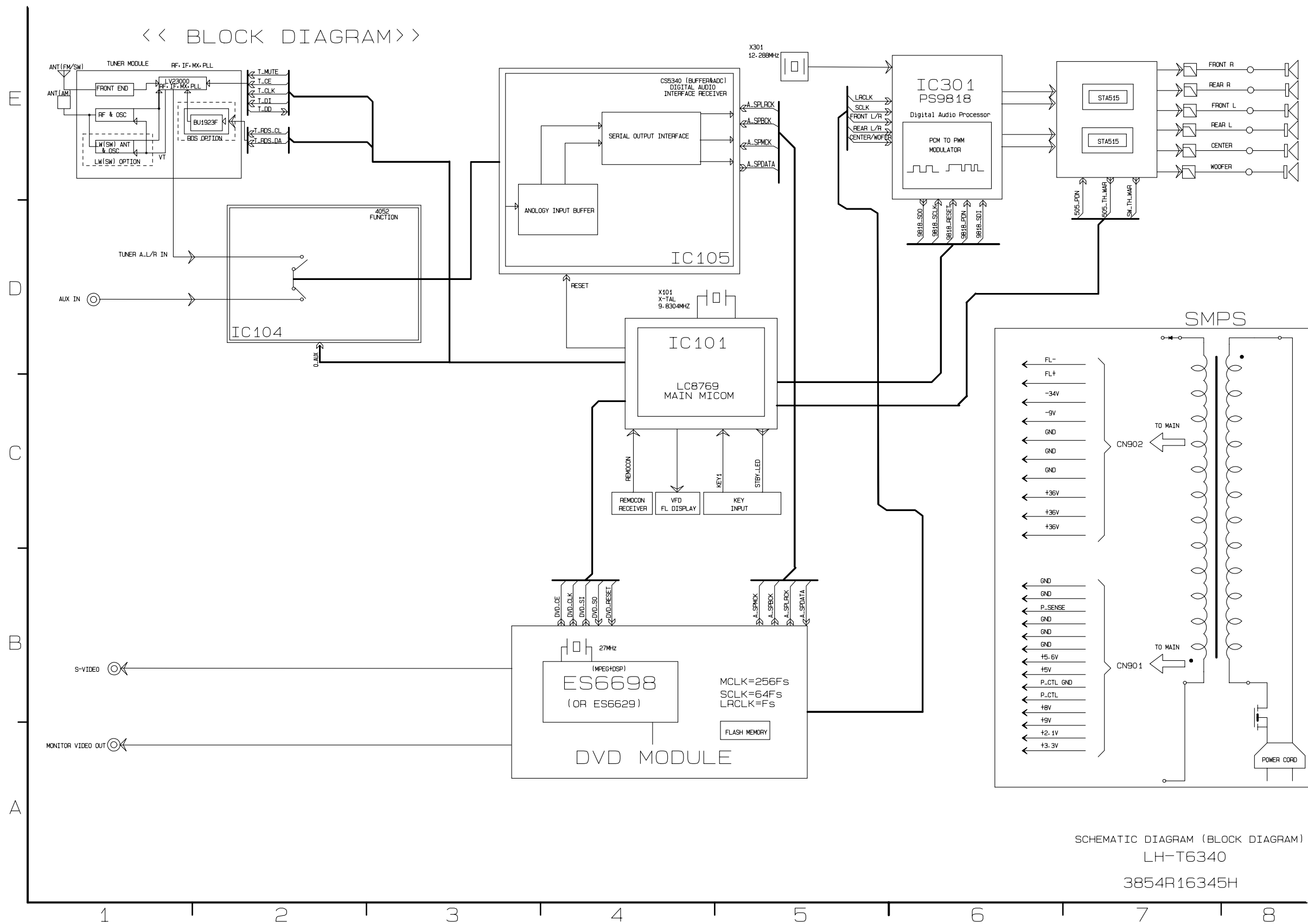
□ MODEL : LHS-T6340T



□ MODEL : LHS-T6340W



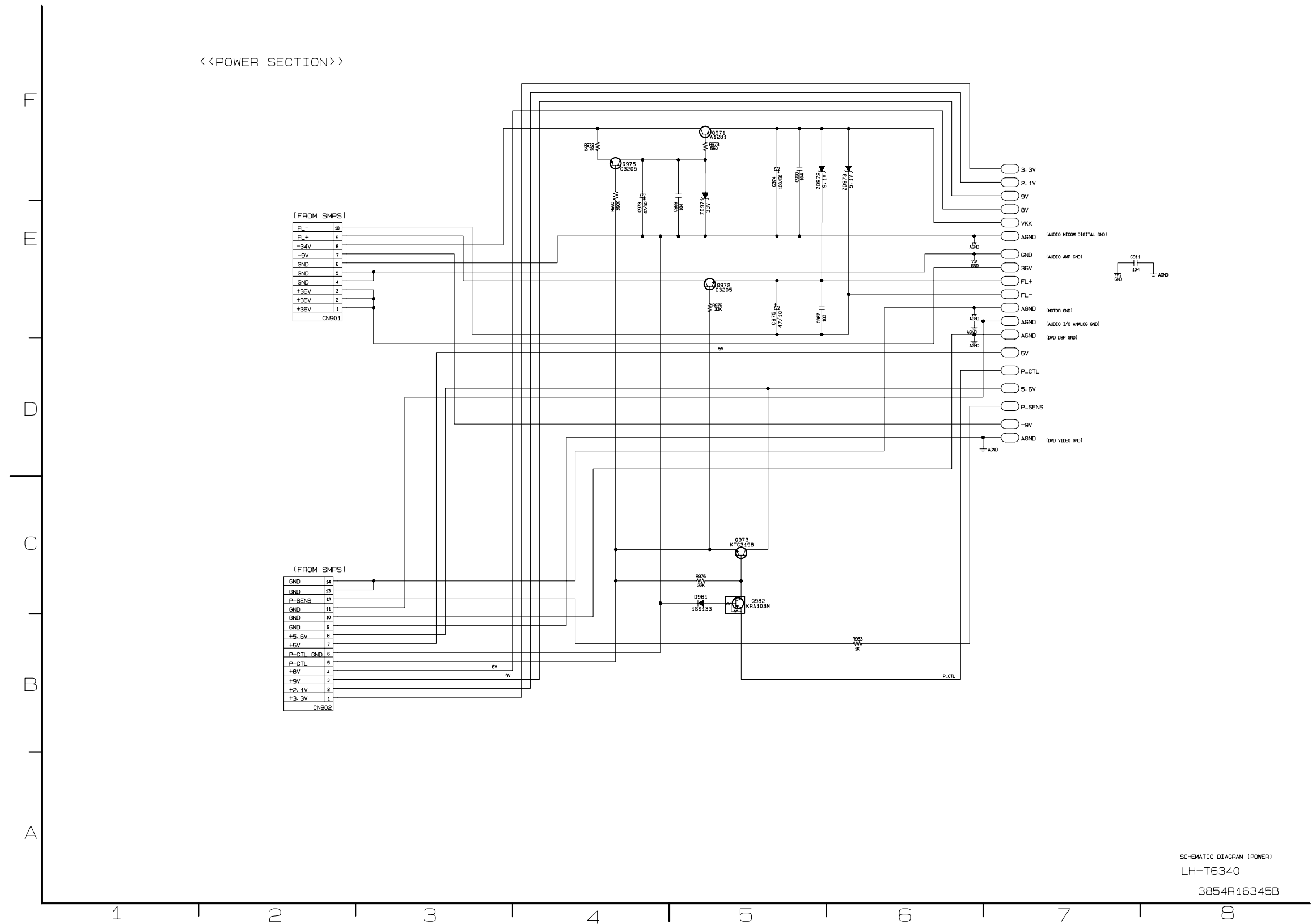
□ BLOCK DIAGRAM



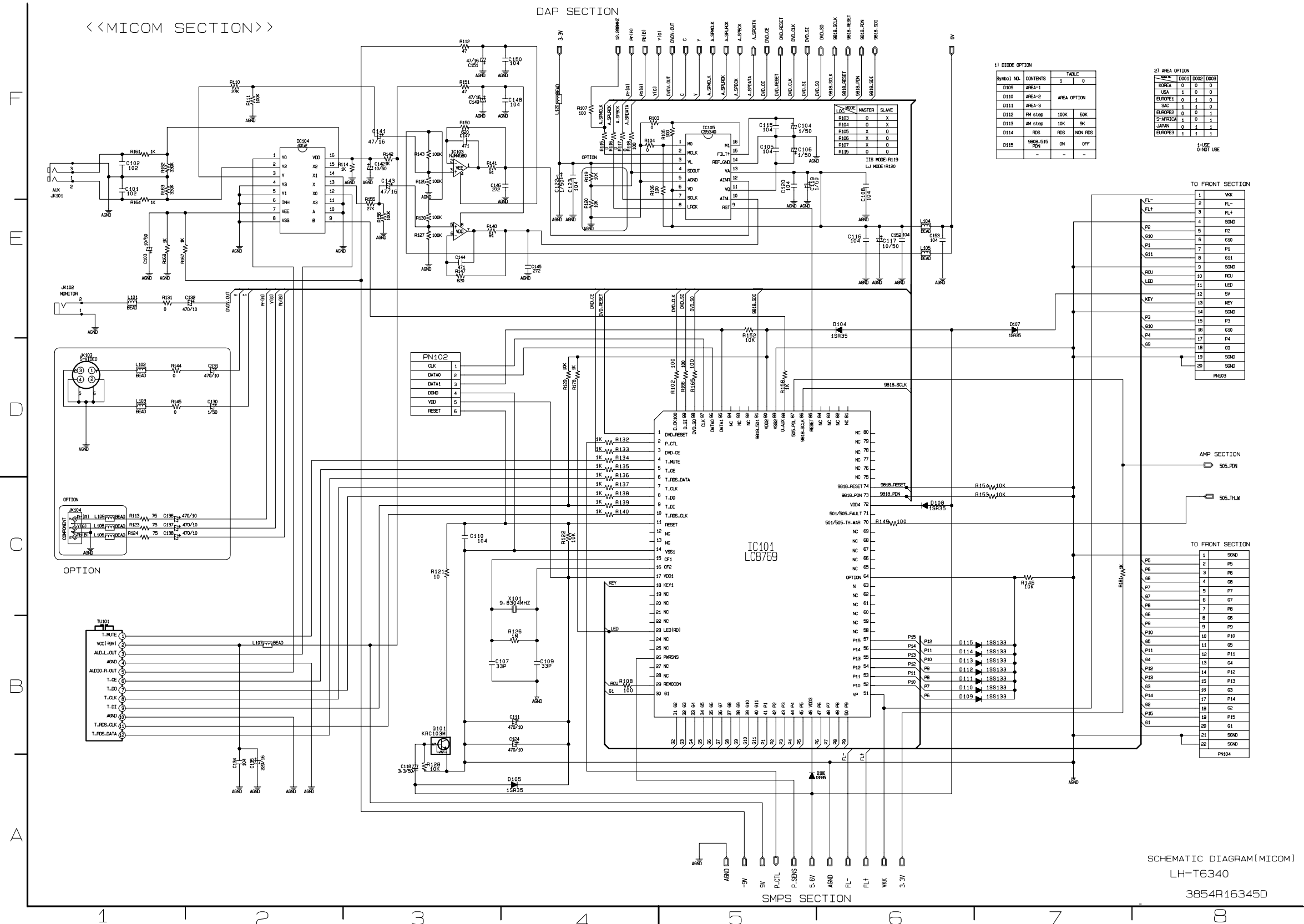
SCHEMATIC DIAGRAM (BLOCK DIAGRAM)
LH-T6340
3854R16345H

SCHEMATIC DIAGRAMS

POWER SCHEMATIC DIAGRAM



• MICOM SCHEMATIC DIAGRAM



1) DODE OPTION

ByModel No.	CONTENTS	TABLE	
		1	0
D109	AREA-1		
D110	AREA-2		
D111	AREA-3		
D112	FM stmb	100K	50K
D113	AM stmb	10K	5K
D114	RES	RES	NON RES
D115	SRCS.DVS PDR	ON	OFF

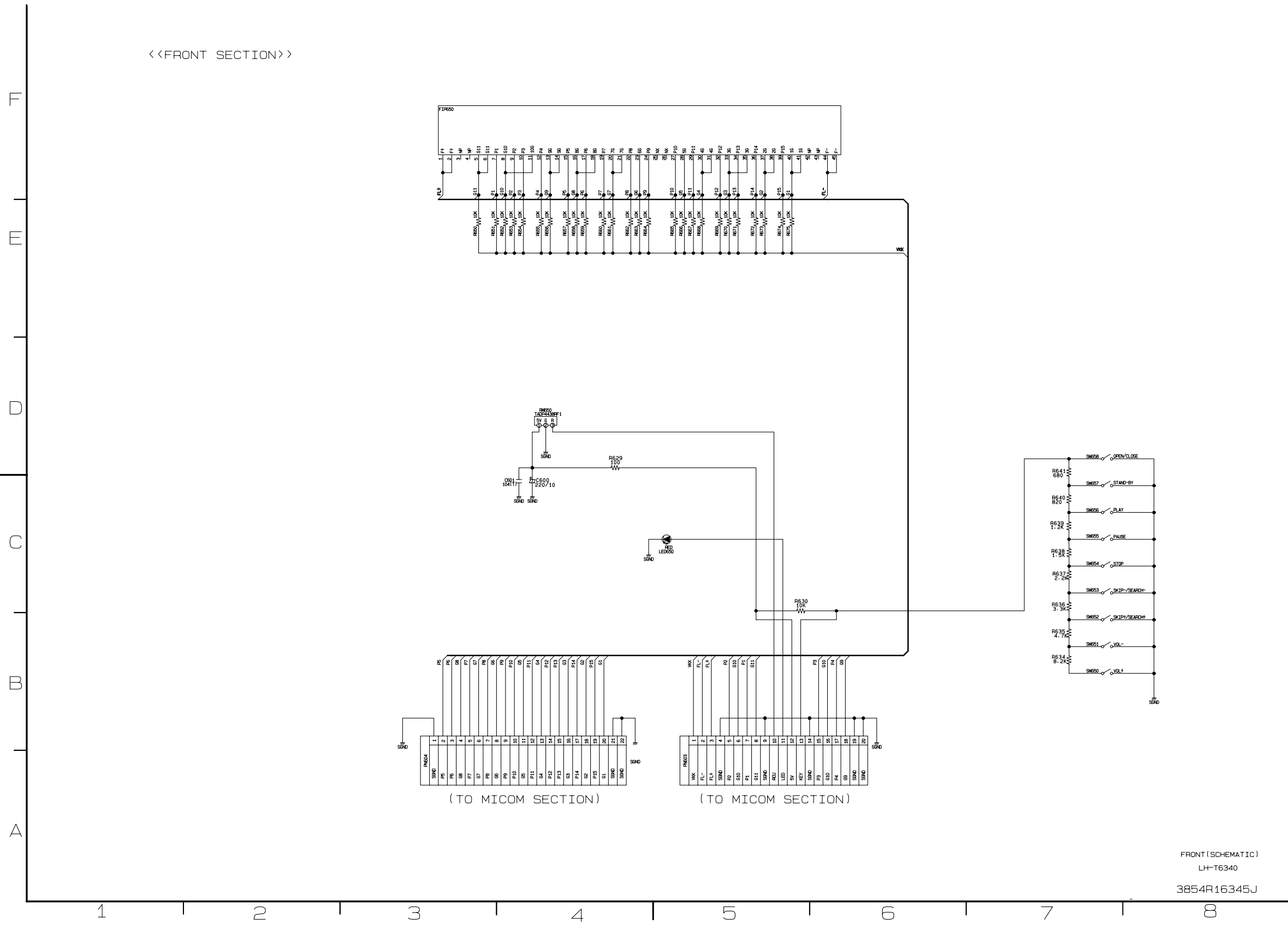
2) AREA OPTION

AREA	D001	D002	D003
KOREA	0	0	0
USA	1	0	0
EUROPE1	0	1	0
SAC	1	1	0
EUROPE2	0	0	1
S-AFRICA	1	0	1
JAPAN	0	1	1
EUROPE3	1	1	1

1:USE
0:NOT USE

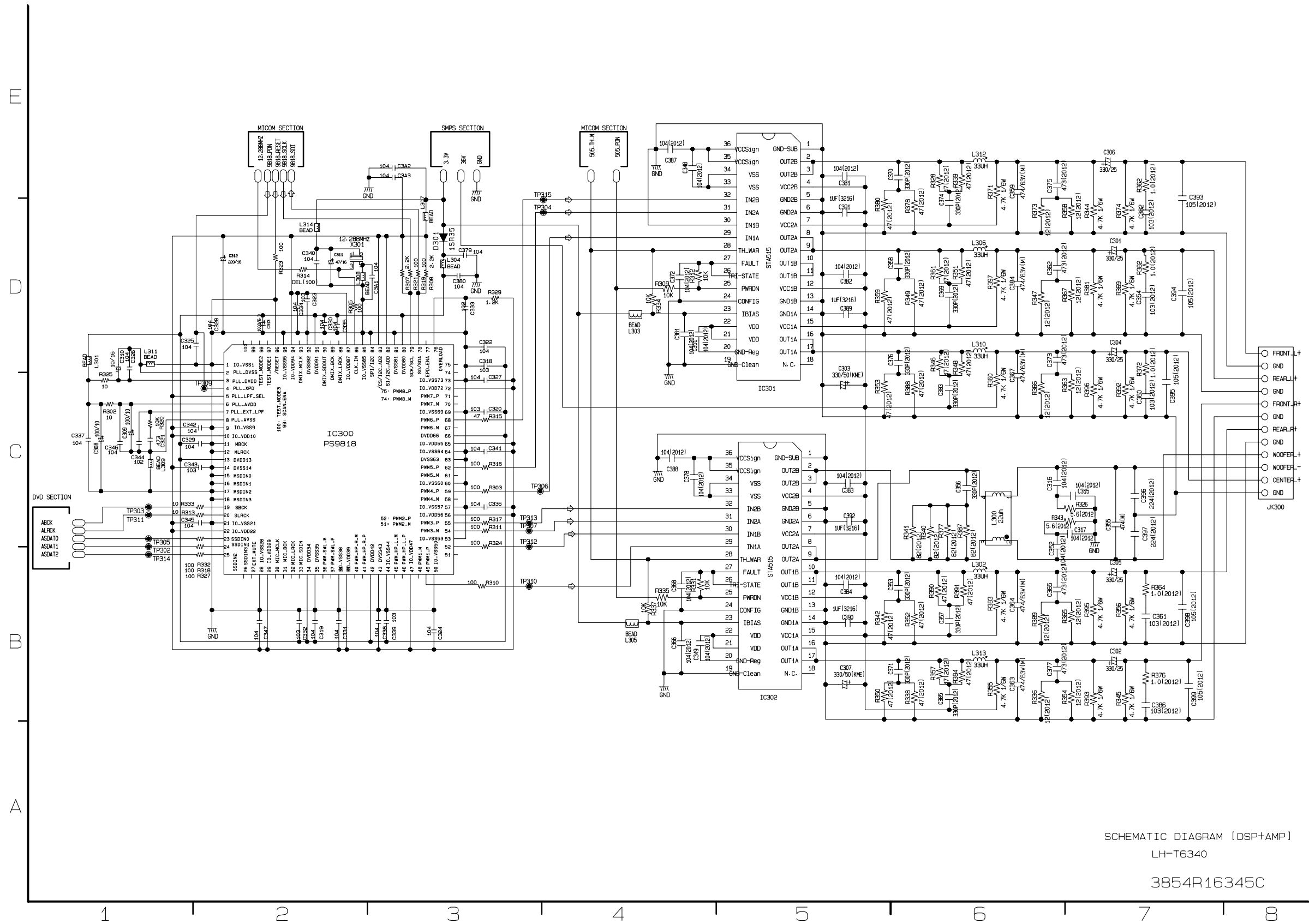
SCHEMATIC DIAGRAM[MICOM]
LH-T6340
3854R16345D

• FRONT SCHEMATIC DIAGRAM



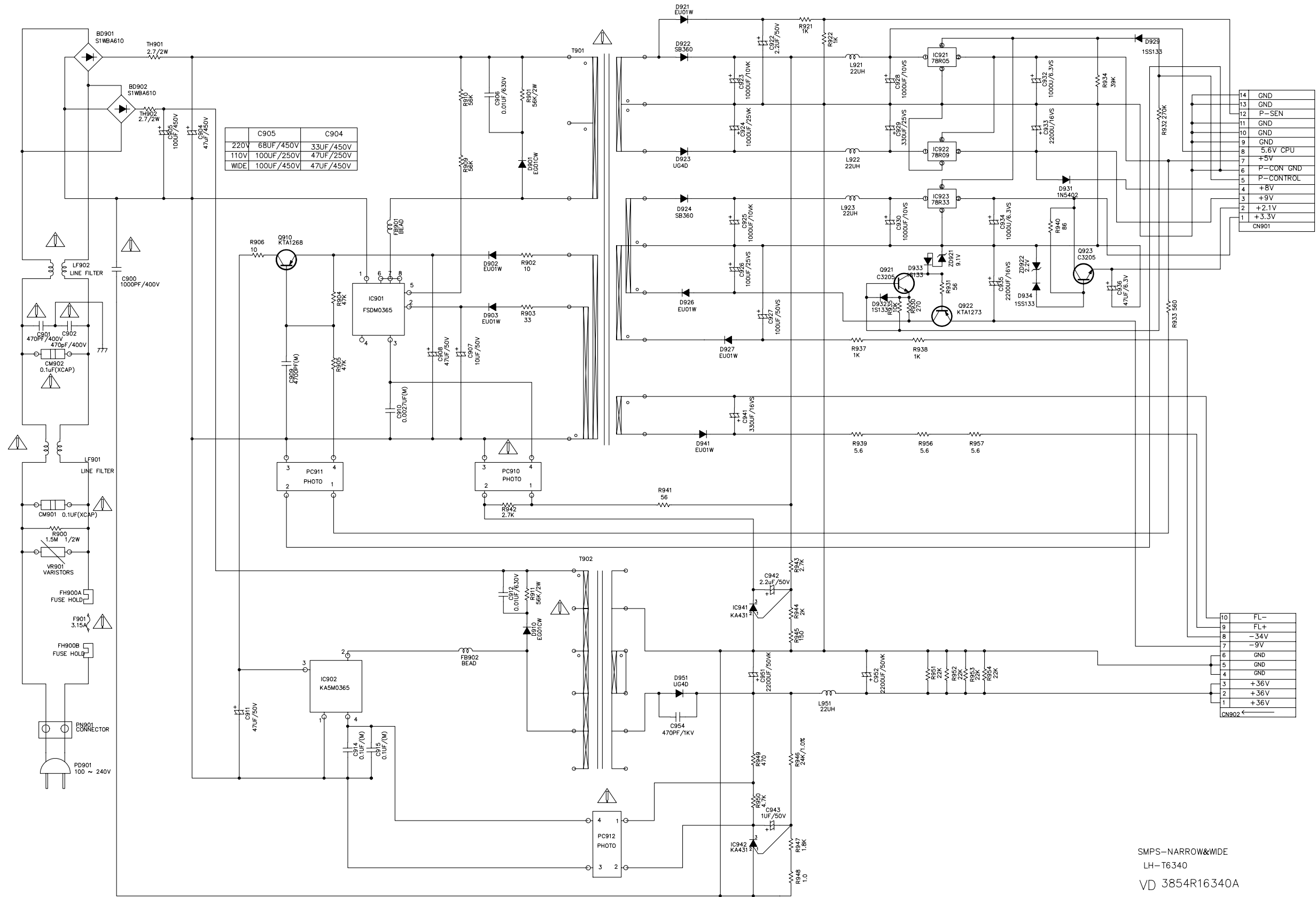
FRONT (SCHEMATIC)
LH-T6340
3854R16345J

DSP& SCHEMATIC DIAGRAM

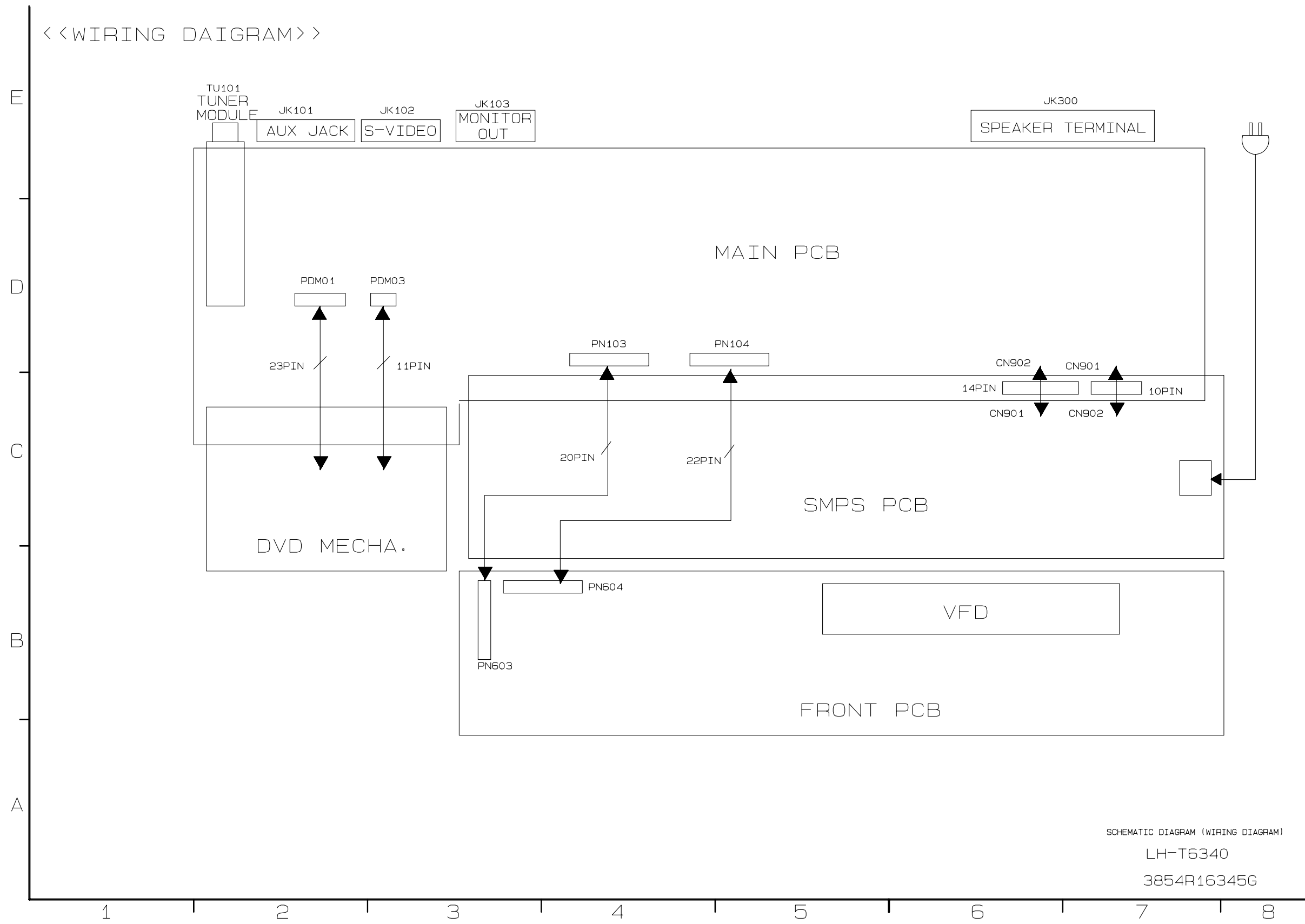


SCHEMATIC DIAGRAM [DSP+AMP]
 LH-T6340
 3854R16345C

• SMPS-NARROW&WIDE SCHEMATIC DIAGRAM



WIRING DIAGRAM



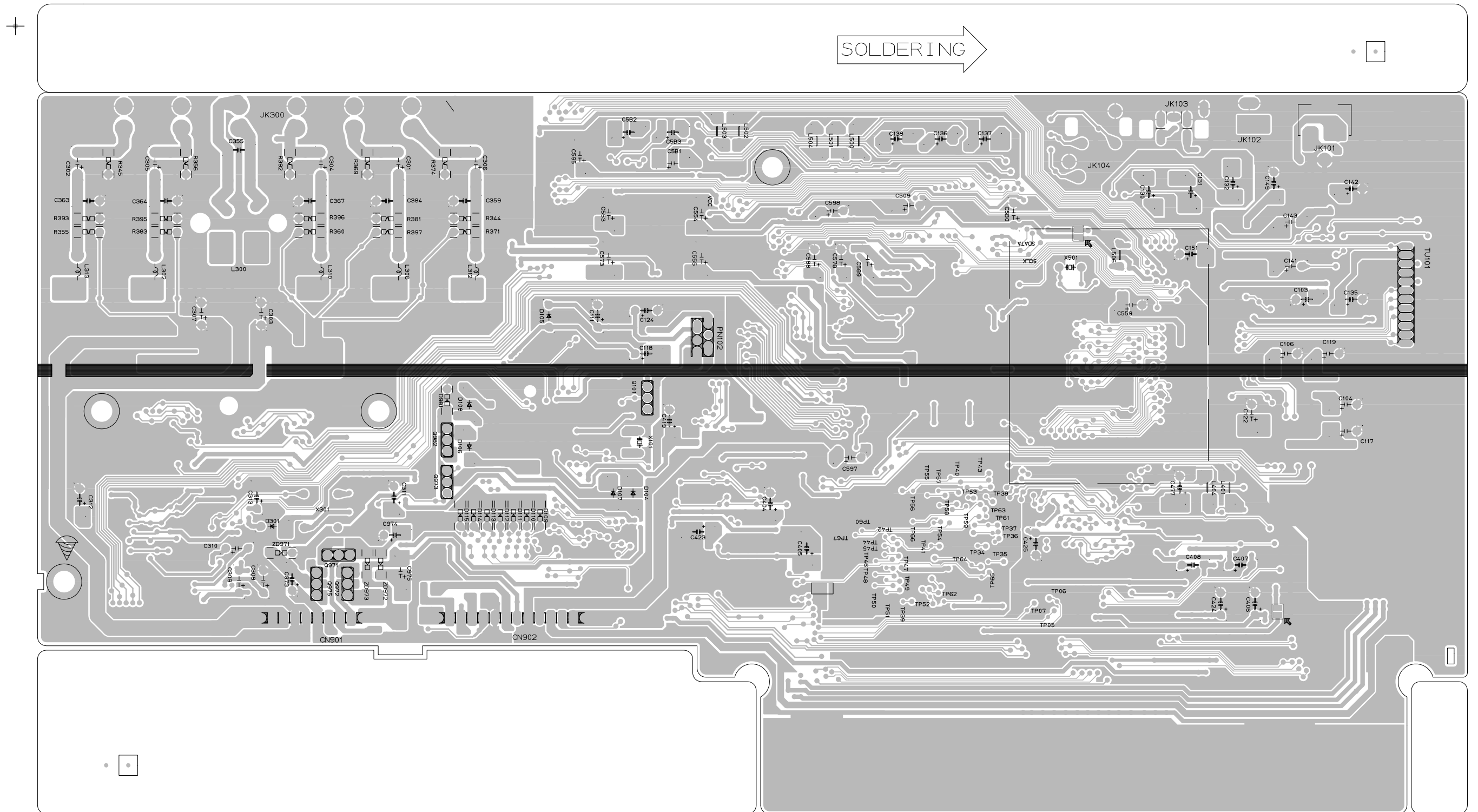
SCHEMATIC DIAGRAM (WIRING DIAGRAM)

LH-T6340

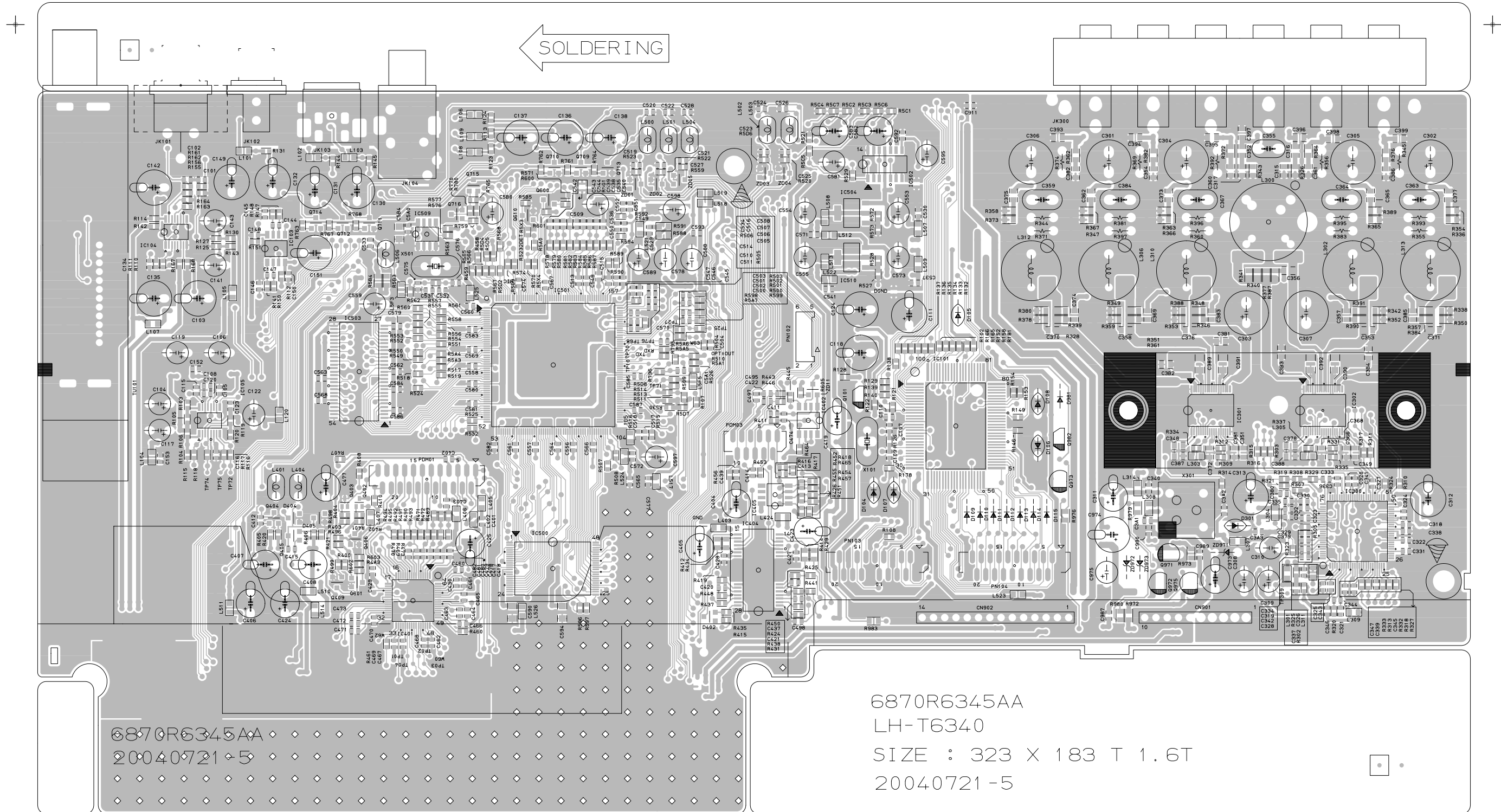
3854R16345G

PRINTED CIRCUIT BOARD DIAGRAMS

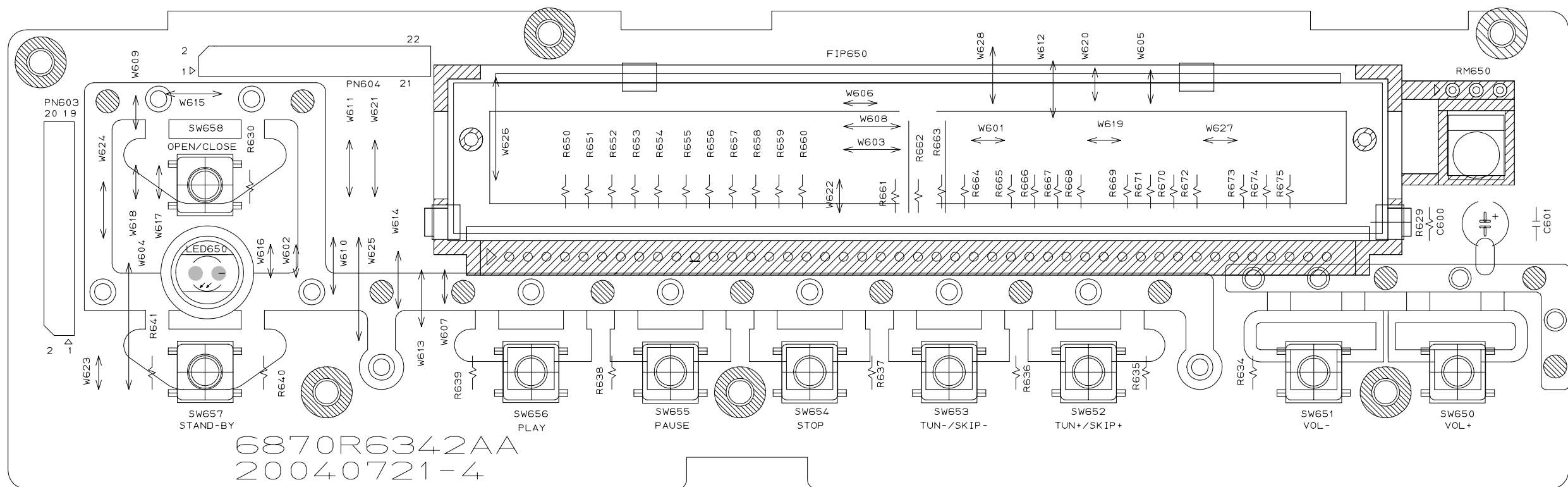
MAIN/DVD P.C. BOARD DIAGRAM (BOTTOM)



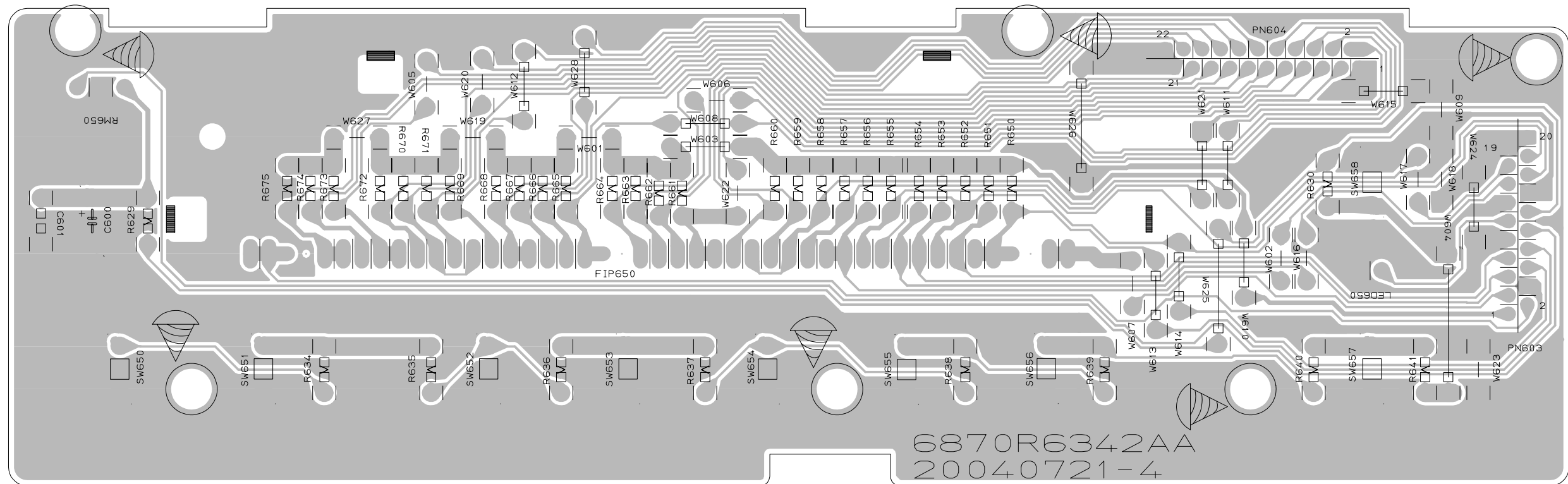
• MAIN/DVD P.C. BOARD DIAGRAM (TOP)



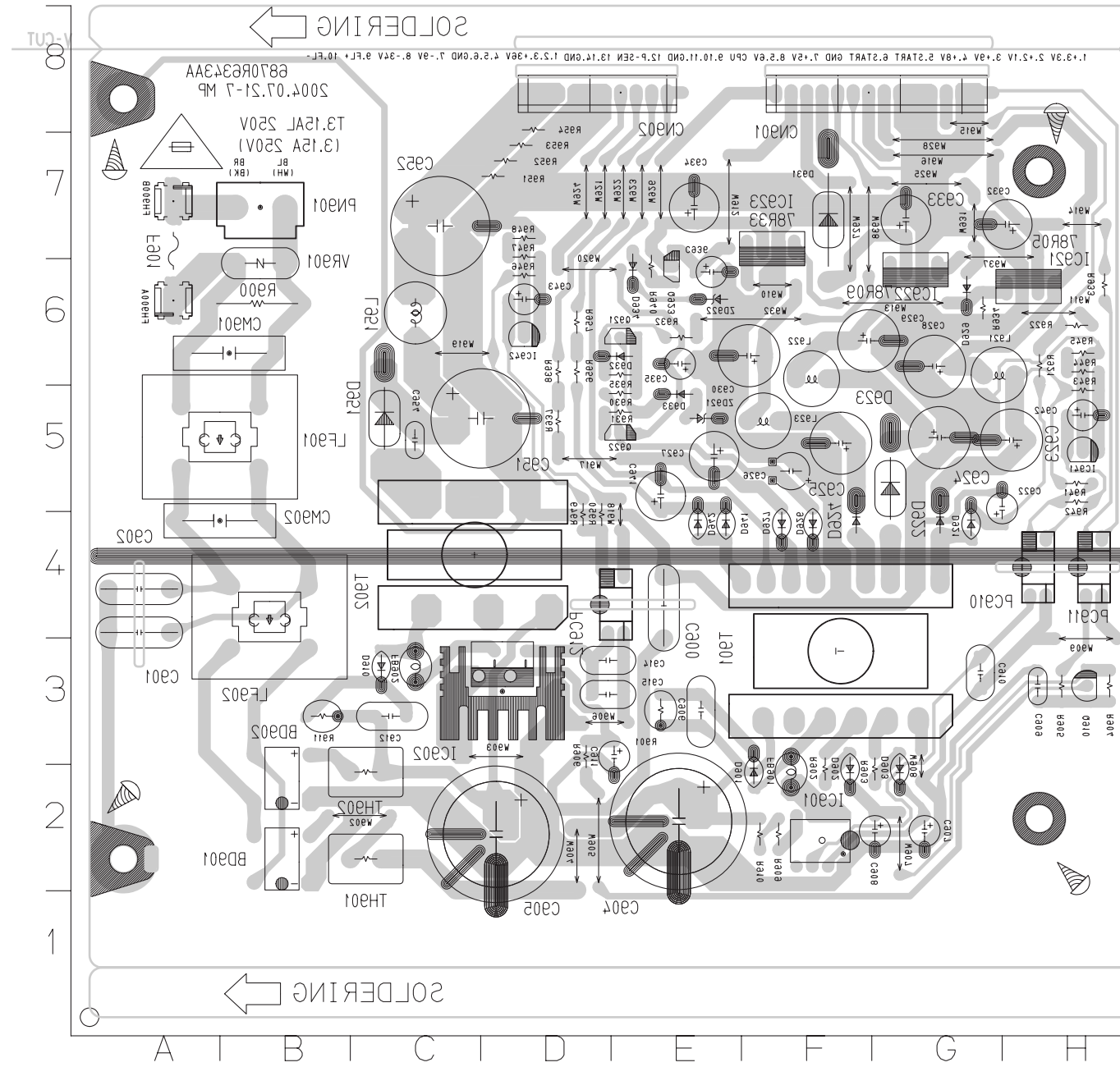
• FRONT P.C. BOARD (BOTTOM)



• FRONT P.C. BOARD (TOP)



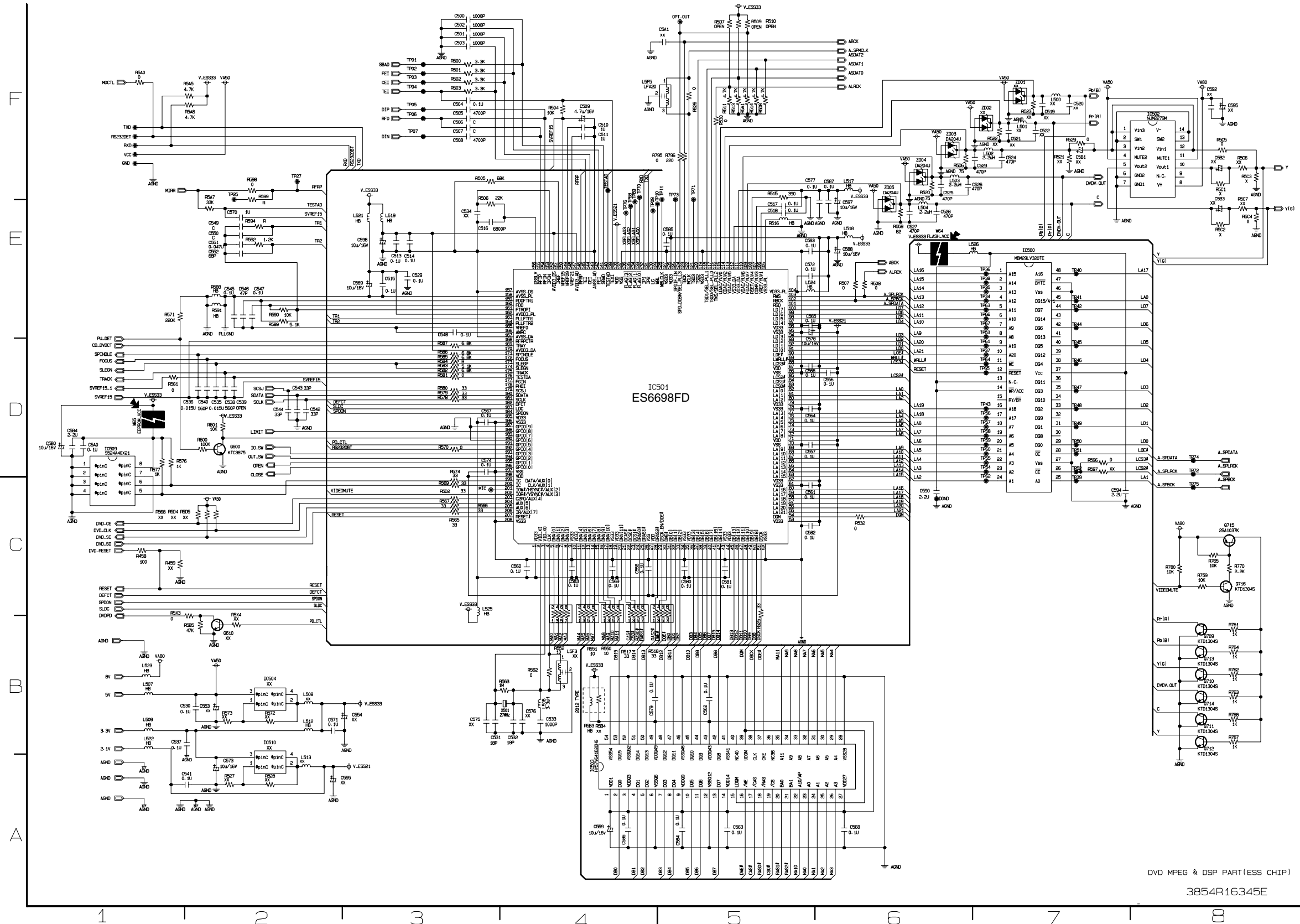
• SMPS P.C. BOARD



BD901	B2	D910	C3	R903	G2
BD902	B2	D921	G4	R904	H3
C900	E4	D922	G4	R905	H3
C901	A4	D923	G5	R906	D3
C902	A4	D924	F4	R909	F2
C904	E2	D926	F4	R910	F2
C905	D2	D927	F4	R911	B3
C906	E3	D929	G6	R921	H6
C907	G2	D931	F7	R922	H6
C908	G2	D932	E6	R930	E5
C909	H3	D933	E5	R931	E5
C910	G3	D934	E6	R932	E6
C911	E3	D941	E4	R933	H6
C912	C3	D942	E4	R934	G6
C914	D3	D951	C5	R935	E6
C915	D3	FB901	F2	R937	D5
C922	H5	FB902	C3	R938	D6
C923	H5	FH900A	A6	R940	E6
C924	G5	FH900B	A7	R941	H5
C925	F5	IC901	F2	R942	H5
C926	F5	IC902	D3	R943	H5
C927	E5	IC921	H6	R944	H6
C928	G6	IC922	G6	R945	H6
C929	F6	IC923	F7	R946	D6
C930	F6	IC941	H5	R947	D7
C932	H7	IC942	D6	R948	D7
C933	G7	L921	G6	R949	D4
C934	E7	L922	F6	R950	D4
C935	E6	L923	F5	R951	D7
C936	E6	L951	C6	R952	D7
C941	E5	LF901	B5	R953	D7
C942	H5	LF902	B4	R954	D8
C943	D6	PC910	H4	R956	D6
C951	D5	PC911	H4	R957	D6
C952	C7	PC912	D4	T901	F3
C954	C5	PN901	B7	T902	C4
CM901	B6	Q910	H3	TH901	C2
CM902	B4	Q921	E6	TH902	C2
CN901	F8	Q922	E5	VR901	B6
CN902	E8	Q923	E6	ZD921	E5
D901	F2	R900	B6	ZD922	E6
D902	F2	R901	E3		
D903	G2	R902	F2		

DVD SCHEMATIC DIAGRAMS

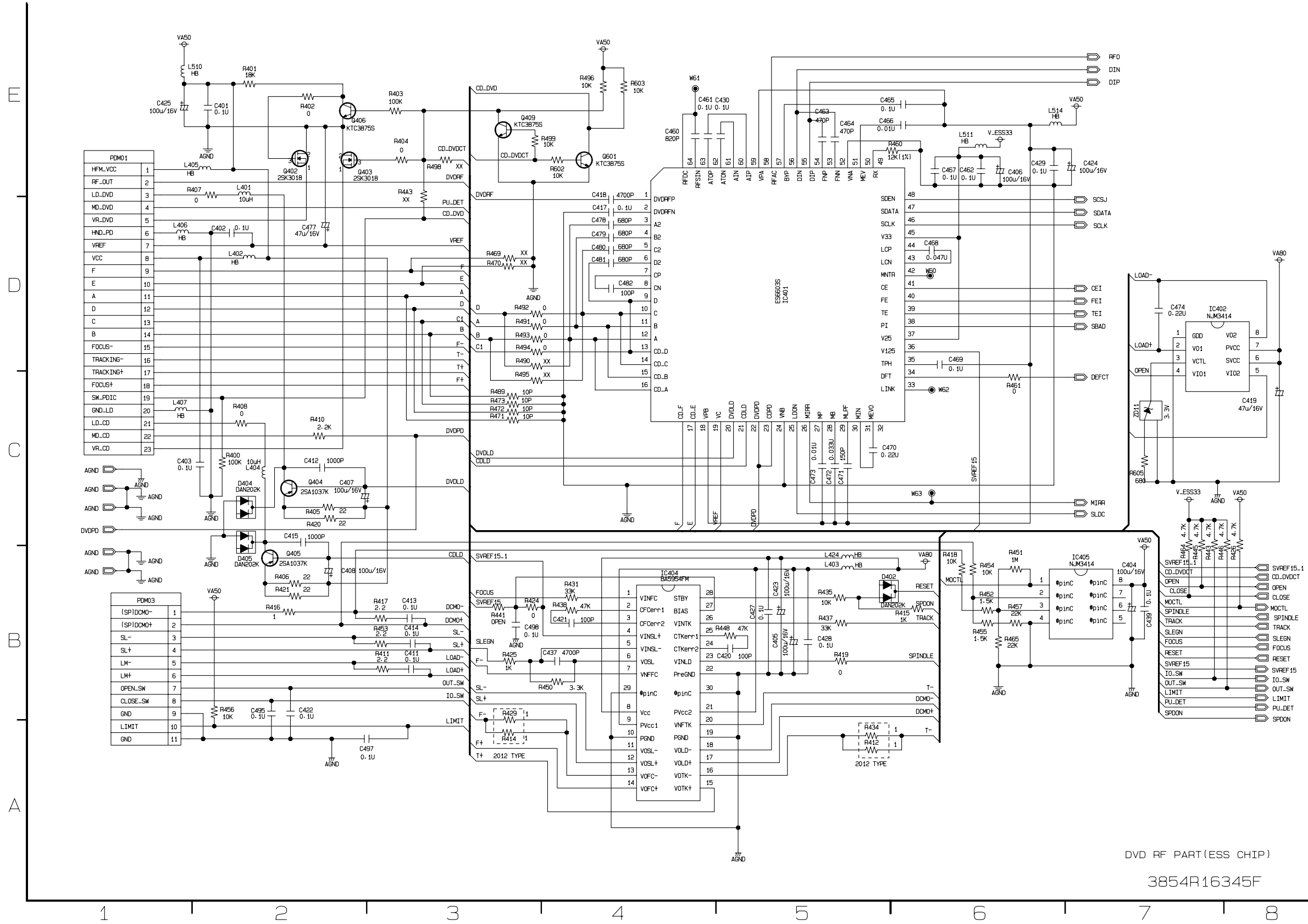
DVD MPEG & DSP SCHEMATIC DIAGRAM



DVD MPEG & DSP PART(ESS CHIP)

3854R16345E

DVD RF SCHEMATIC DIAGRAM

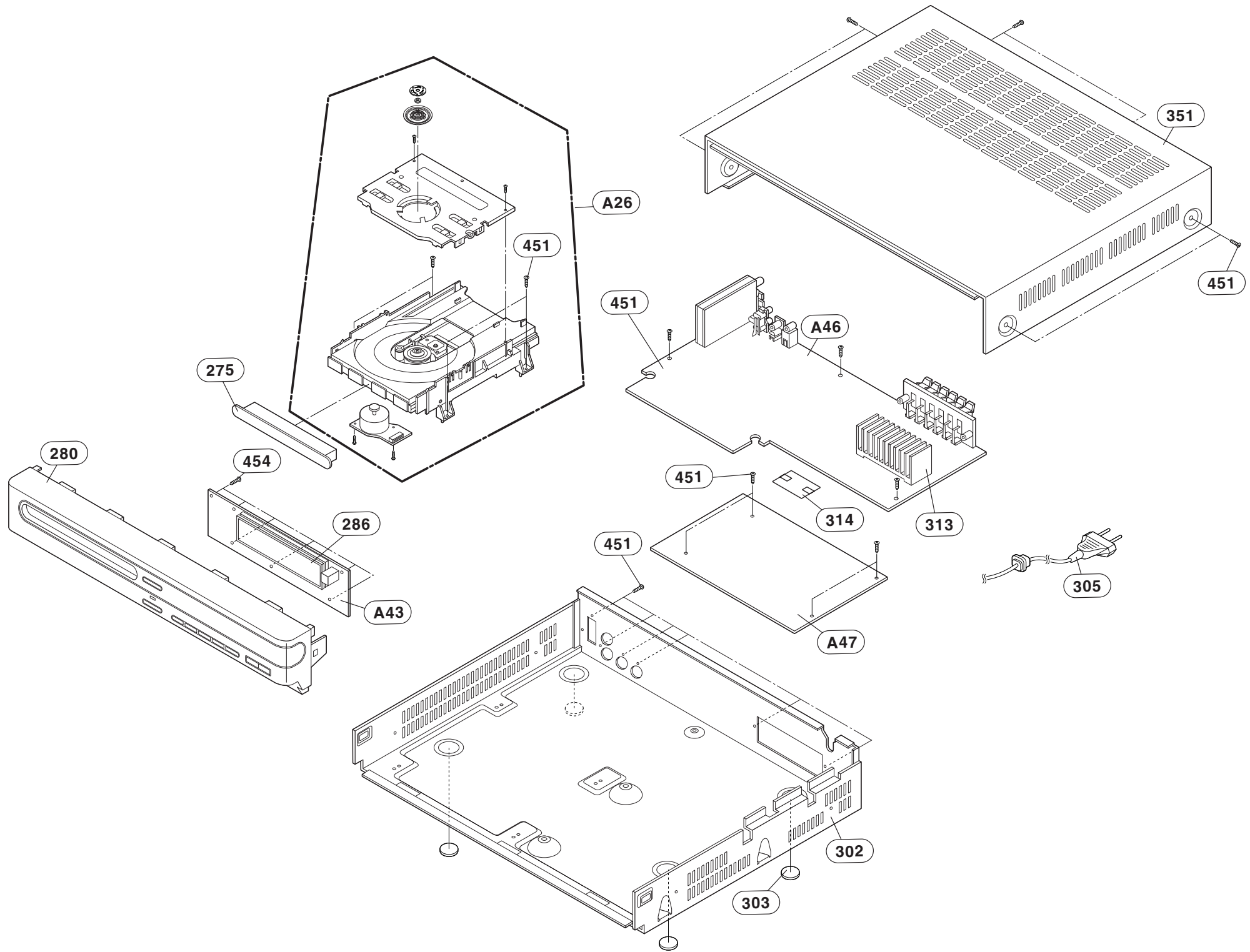


DVD RF PART (ESS CHIP)

3854R16345F

SECTION 4. EXPLODED VIEWS

□ CABINET AND MAIN FRAME SECTION



• DECK MECHANISM EXPLODED VIEW

